

3.3 V ECL 4-Input OR/NOR MC100LVEL01

Description

The MC100LVEL01 is a 4-input OR/NOR gate. The device is functionally equivalent to the EL01 device and works from a 3.3 V supply. With AC performance similar to the EL01 device, the LVEL01 is ideal for low voltage applications which require the ultimate in AC performance.

Features

- 370 ps Propagation Delay
- High Bandwidth Output Transitions
- ESD Protection:
 - ♦ > 2 kV Human Body Model
 - ♦ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range: V_{CC} = 0 V with $V_{EE} = -3.0 \text{ V}$ to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at V_{FF}
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity
 - ♦ Level 1 for SOIC-8
 - ◆ For Additional Information, see Application Note <u>AND8003/D</u>
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index 28 to 34
- Transistor Count = 83 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

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MARKING DIAGRAM*



A = Assembly Location

= Wafer Lot

Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

| Device | Package | Shipping† |
|-----------------|---------------------|---------------------|
| MC100LVEL01DR2G | SOIC-8 (Pb-Free) | 2500 Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MC100LVEL01

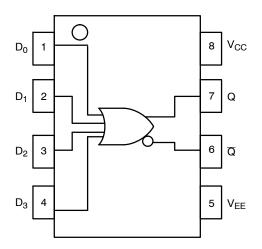


Table 1. PIN DESCRIPTION

| PIN | FUNCTION | |
|---|--|--|
| D0-D3 Q, Q V _{CC} V _{EE} | ECL Data Inputs ECL Data Outputs Positive Supply Negative Supply | |

Figure 1. Logic Diagram and Pinout Assignment

Table 2. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Units |
|------------------|--|--|---|-------------------|-------|
| V _{CC} | PECL Mode Power Supply | V _{EE} = 0 V | | 8 to 0 | V |
| V _{EE} | NECL Mode Power Supply | V _{CC} = 0 V | | -8 to 0 | V |
| VI | PECL Mode Input Voltage NECL Mode Input Voltage | V _{EE} = 0 V V _{CC} = 0 V | V _I ≤ V _{CC} V _I ≥V _{EE} | 6 to 0 -6 to 0 | V |
| l _{out} | Output Current | Continuous Surge | | 50 100 | mA |
| T _A | Operating Temperature Range | | | -40 to +85 | °C |
| T _{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θЈА | Thermal Resistance (Junction-to-Ambient) | 0 lfpm 500 lfpm | | 190 130 | °C/W |
| θ _{JC} | Thermal Resistance (Junction-to-Case) | Standard Board | | 41 to 44 ±5% | °C/W |
| T _{sol} | Wave Solder (Pb-Free) | < 2 to 3 sec @ 260°C | | 265 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MC100LVEL01

Table 3. LVPECL DC CHARACTERISTICS ($V_{CC} = 3.3 \text{ V}; V_{EE} = 0 \text{ V} \text{ (Note 1))}$

| | | -40°C | | 25°C | | | 85°C | | | | |
|-----------------|------------------------------|-------|------|------|------|------|------|------|------|------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| I _{EE} | Power Supply Current 15 20 | | | 15 | 20 | | 17 | 22 | mA | | |
| V _{OH} | Output HIGH Voltage (Note 2) | 2215 | 2295 | 2420 | 2275 | 2345 | 2420 | 2275 | 2345 | 2420 | mV |
| V _{OL} | Output LOW Voltage (Note 2) | 1470 | 1605 | 1745 | 1490 | 1595 | 1680 | 1490 | 1595 | 1680 | mV |
| V _{IH} | Input HIGH Voltage | 2135 | | 2420 | 2135 | | 2420 | 2135 | | 2420 | mV |
| V_{IL} | Input LOW Voltage | 1490 | | 1825 | 1490 | | 1825 | 1490 | | 1825 | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μΑ |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.5 | | | μΑ |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $\pm 0.3~V$.
- 2. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.

Table 4. LVNECL DC CHARACTERISTICS ($V_{CC} = 0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 1))

| | | -40°C | | 25°C | | | 85°C | | | | |
|-----------------|------------------------------|-------|-------|-------|-------|-------|-------|-------|-------|-------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| I _{EE} | Power Supply Current 15 20 | | | 15 | 20 | | 17 | 22 | mA | | |
| V _{OH} | Output HIGH Voltage (Note 2) | -1085 | -1005 | -880 | -1025 | -955 | -880 | -1025 | -955 | -880 | mV |
| V _{OL} | Output LOW Voltage (Note 2) | -1830 | -1695 | -1555 | -1810 | -1705 | -1620 | -1810 | -1705 | -1620 | mV |
| V _{IH} | Input HIGH Voltage | -1165 | | -880 | -1165 | | -880 | -1165 | | -880 | mV |
| V_{IL} | Input LOW Voltage | -1810 | | -1475 | -1810 | | -1475 | -1810 | | -1475 | mV |
| I _{IH} | Input HIGH Current | | | 150 | | | 150 | | | 150 | μΑ |
| I _{IL} | Input LOW Current | 0.5 | | | 0.5 | | | 0.5 | | | μΑ |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary ±0.3 V. 2. Outputs are terminated through a 50 Ω resistor to V_{CC} –2 volts.

Table 5. AC CHARACTERISTICS ($V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0 \text{ V}$ or $V_{CC} = 0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 1))

| | | -40°C | | 25°C | | | 85°C | | | | |
|--------------------------------------|------------------------------------|-------|-----|------|-----|-----|------|-----|-----|-----|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| f _{max} | Maximum Toggle Frequency | | 1.6 | | | 1.6 | | | 1.6 | | GHz |
| t _{PLH} t _{PHL} | Propagation Delay to Output | 210 | 310 | 510 | 270 | 370 | 470 | 290 | 390 | 490 | ps |
| t _{skew} | Within Device Skew | | 40 | 100 | | 40 | 100 | | 40 | 100 | ps |
| t _{JITTER} | Cycle-to-Cycle Jitter | | 7.1 | | | 7.4 | | | 7.6 | | ps |
| t _r t _f | Output Rise/Fall Times Q (20%-80%) | 120 | 225 | 320 | 120 | 225 | 320 | 120 | 225 | 320 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. V_{EE} can vary ±0.3 V.

MC100LVEL01

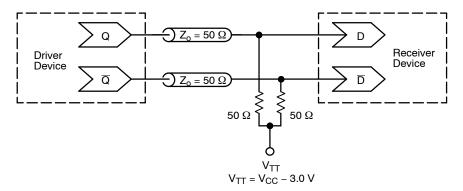


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices)

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

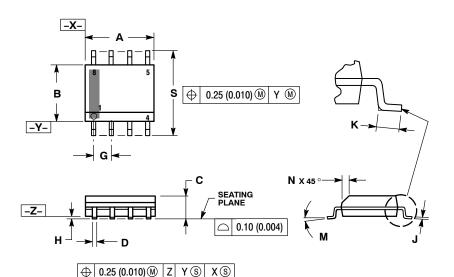
AND8090/D - AC Characteristics of ECL Devices





SOIC-8 NB CASE 751-07 **ISSUE AK**

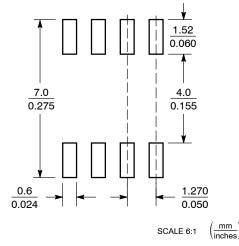
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- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

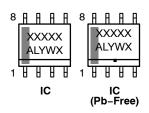
| | MILLIMETERS | | INCHES | | | | |
|-----|-------------|-------|-----------|-------|--|--|--|
| DIM | MIN | MAX | MIN | MAX | | | |
| Α | 4.80 | 5.00 | 0.189 | 0.197 | | | |
| В | 3.80 | 4.00 | 0.150 | 0.157 | | | |
| С | 1.35 | 1.75 | 0.053 | 0.069 | | | |
| D | 0.33 | 0.51 | 0.013 | 0.020 | | | |
| G | 1.27 | 7 BSC | 0.050 BSC | | | | |
| Н | 0.10 | 0.25 | 0.004 | 0.010 | | | |
| J | 0.19 | 0.25 | 0.007 | 0.010 | | | |
| K | 0.40 | 1.27 | 0.016 | 0.050 | | | |
| М | 0 ° | 8 ° | 0 ° | 8 ° | | | |
| N | 0.25 | 0.50 | 0.010 | 0.020 | | | |
| S | 5.80 | 6.20 | 0.228 | 0.244 | | | |

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location = Wafer Lot

= Year = Work Week W = Pb-Free Package

XXXXXX XXXXXX AYWW AYWW H \mathbb{H} Discrete **Discrete** (Pb-Free)

XXXXXX = Specific Device Code = Assembly Location Α

ww = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may

not follow the Generic Marking.

STYLES ON PAGE 2

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DATE 16 FEB 2011

| STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER | STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1 | STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1 | STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE |
|--|---|--|---|
| STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE | PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE | PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd | PIN 1. COLLECTOR, DIE #1 2. BASE, #1 |
| STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON | STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND | STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 | STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 9. DRAIN |
| STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN | STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN | STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON | STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1 |
| STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC | STYLE 18: PIN 1. ANODE 2. ANODE | STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 | STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN |
| 3. V10UT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6 | STYLE 22: | 7. DRAIN 1 8. MIRROR 1 STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT | STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE |
| STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT | STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC | STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN | STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN |
| STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1 | STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1 | | |

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